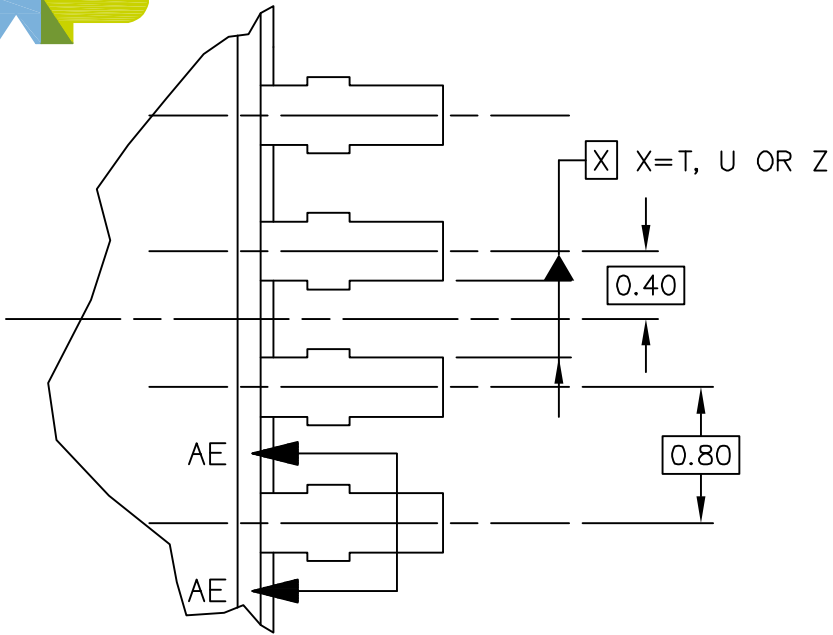
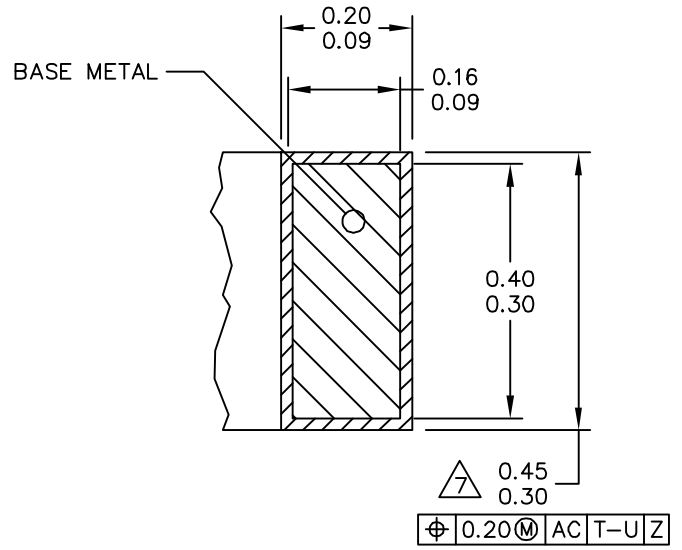


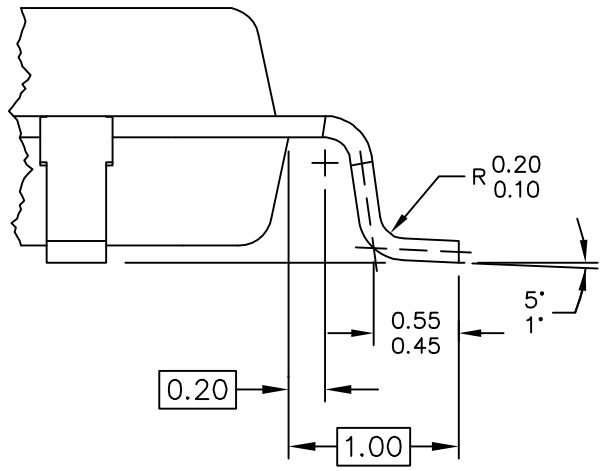
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TITLE: 64 LD TQFP, 14X14 PKG, 0.8 PITCH, 1.4 THICK	DOCUMENT NO: 98ASS23231W	REV: C
	STANDARD: NON-JEDEC	
	SOT791-2	25 JAN 2016



DETAIL "A-A"



SECTION AE-AE



DETAIL "AD"

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	STANDARD: NON-JEDEC	
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NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M–1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE AB IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUM T, U AND Z TO BE DETERMINED AT DATUM PLANE AB.
5. THIS DIMENSIONS TO BE DETERMINED AT SEATING PLANE AC.
6. THIS DIMENSIONS DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 PER SIDE. THIS DIMENSIONS DOES INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE AB.
7. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE THIS DIMENSION TO EXCEED 0.53.

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